PGA970 LVDT Sensor Signal Conditioner

1 Features

- Analog features
  - Programmable-gain analog front end for LVDT sensors
  - Excitation waveform generator and amplifier
  - Dual 24-bit ADC with amplitude and phase demodulators
  - 24-bit auxilary ADC
  - On-chip internal temperature sensor
  - 14-bit output DAC with programmable gain
  - Built-in diagnostics
- Digital features
  - ARM® Cortex®-M0 microcontroller
  - 16KB ferroelectric RAM (FRAM) program memory
  - 2KB general-pupose RAM
  - 512B RAM waveform-generator look-up table
  - 8-MHz on-chip oscillator
- Peripheral features
  - Serial peripheral interface (SPI)
  - One-wire interface (OWI)
  - Ratiometric and absolute voltage output
- General features
  - Operational supply range: 3.5 V to 30 V
  - Ambient temperature range: –40°C to +125°C
  - DMOS gate controller for extended supply range >30 V

2 Applications

- Position sensor signal conditioning
- Linear variable differential transformer (LVDT)
- Rotational variable differential transformer (RVDT)
- Resolver
- RLC measurement

3 Description

The PGA970 is a highly integrated system-on-chip LVDT sensor-signal conditioner with advanced signal-processing capabilities. It contains a three-channel, low-noise, programmable-gain, analog front end that allows direct connection to the sense element, followed by three independent 24-bit delta-sigma ADCs.

Further, the device contains a digital signal-demodulation block that interfaces to an integrated ARM-Cortex M0 MCU, allowing implementation of custom sensor-compensation algorithms stored in the device nonvolatile memory. External system communication is achieved by using any of the SPI, OWI, GPIO, or PWM digital interfaces. Analog output is supported through a 14-bit DAC and programmable-gain amplifier offering reference or absolute-voltage output. Sensing-element excitation is achieved by the use of an integrated waveform generator and waveform amplifier. The waveform signal data is user-defined and stored in a designated RAM memory area.

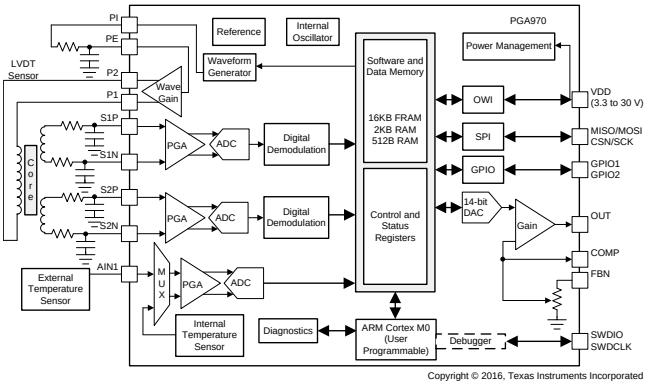
Besides the primary functional components, the PGA970 is equipped with additional support circuitry. The device diagnostics, sensor diagnostics, and integrated temperature sensor provide protection and information about the integrity of the overall system and sensing element. The device also includes a gate-controller circuit which when used with an external depletion MOSFET can regulate the device supply voltage in systems where the supply voltage exceeds 30 V.

Device Information(1)

ORDER NUMBER	PACKAGE	BODY SIZE (NOM)
PGA970QPHPR	HTQFP (48)	7.00 mm × 7.00 mm
PGA970QPHPT		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Diagram



4 Device and Documentation Support

4.1 Documentation Support

4.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *PGA970 GUI* user's guide
- Texas Instruments, *PGA970 Software Quick Start Guide* user's guide
- Texas Instruments, *PGA970 Software* user's guide
- Texas Instruments, *PGA970EVM* user's guide

4.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

4.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

4.4 Trademarks

E2E is a trademark of Texas Instruments.
ARM, Cortex are registered trademarks of ARM Limited.
All other trademarks are the property of their respective owners.

4.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most-current data available for the designated device. This data is subject to change without notice and without revision of this document. For browser-based versions of this data sheet, see the left-hand navigation pane.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
PGA970QPHPR	Active	Production	HTQFP (PHP) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	PGA970Q
PGA970QPHPR.A	Active	Production	HTQFP (PHP) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	PGA970Q
PGA970QPHPRG4	Active	Production	HTQFP (PHP) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	PGA970Q
PGA970QPHPRG4.A	Active	Production	HTQFP (PHP) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	PGA970Q

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

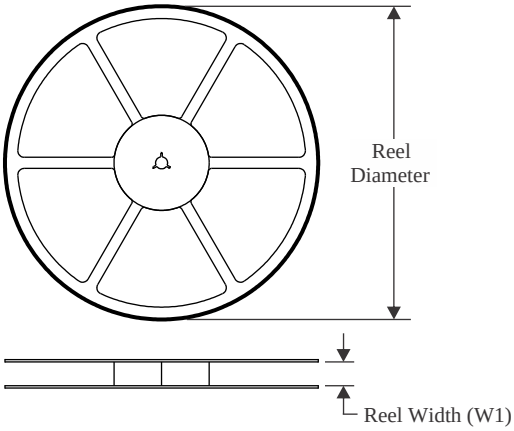
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

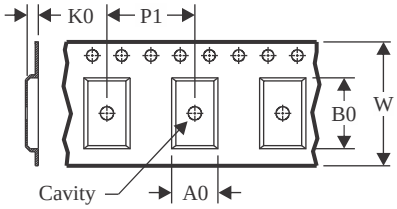
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

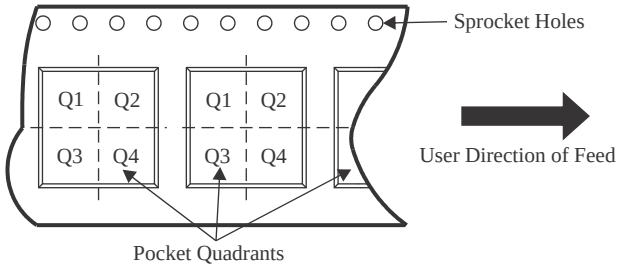


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

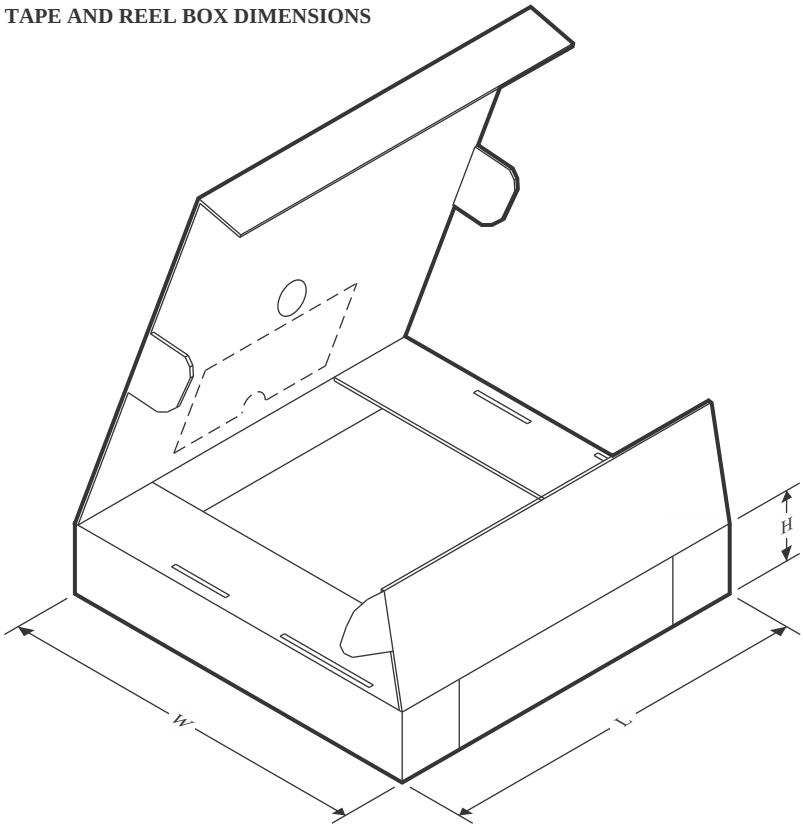
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PGA970QPHPR	HTQFP	PHP	48	1000	330.0	16.4	9.6	9.6	1.5	12.0	16.0	Q2
PGA970QPHPRG4	HTQFP	PHP	48	1000	330.0	16.4	9.6	9.6	1.5	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PGA970QPHPR	HTQFP	PHP	48	1000	350.0	350.0	43.0
PGA970QPHPRG4	HTQFP	PHP	48	1000	350.0	350.0	43.0

GENERIC PACKAGE VIEW

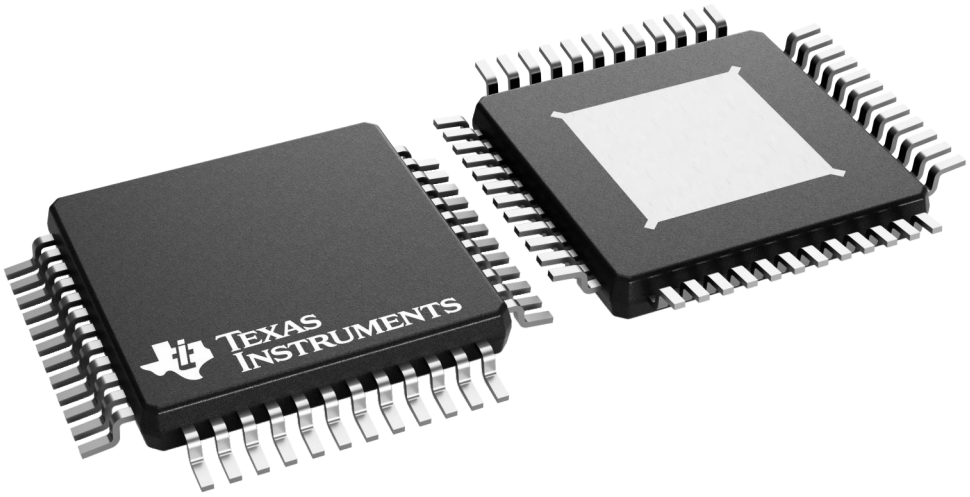
PHP 48

TQFP - 1.2 mm max height

7 x 7, 0.5 mm pitch

QUAD FLATPACK

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



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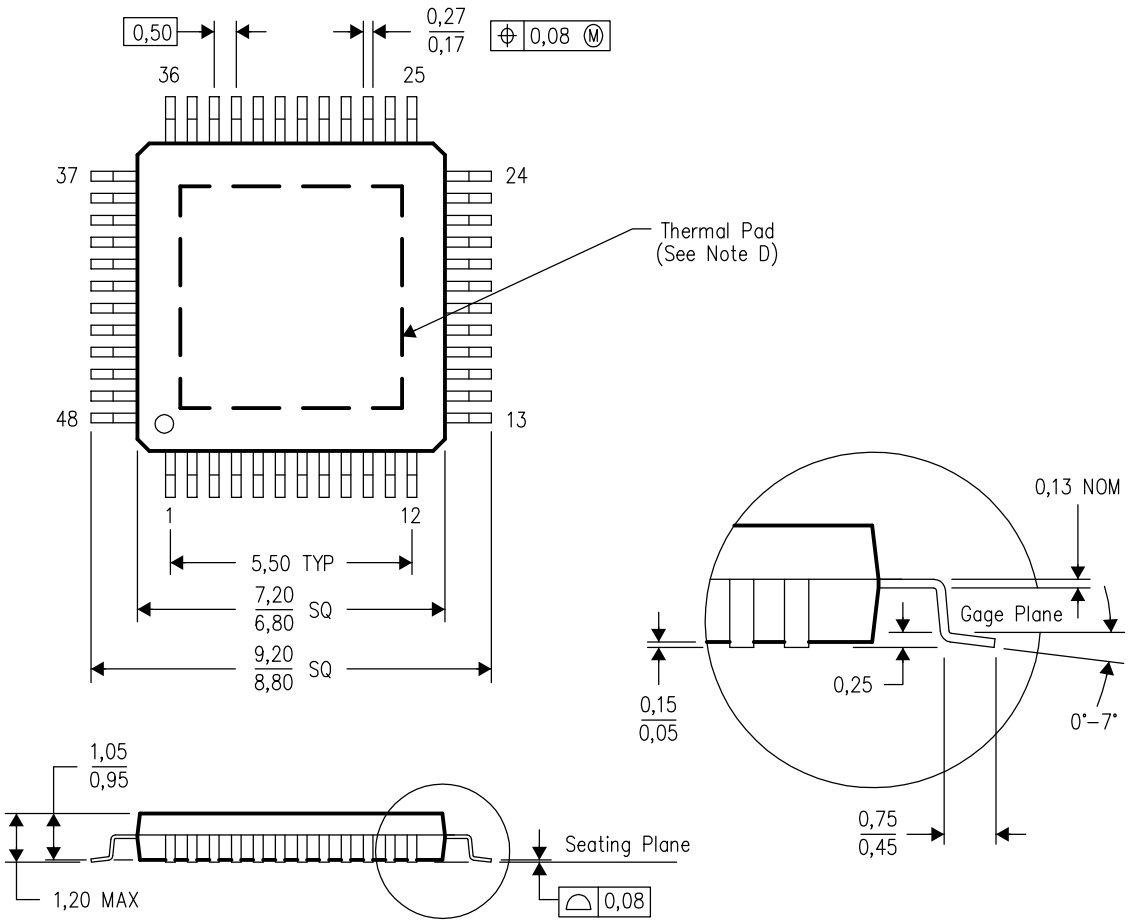
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MS–026

PowerPAD is a trademark of Texas Instruments.

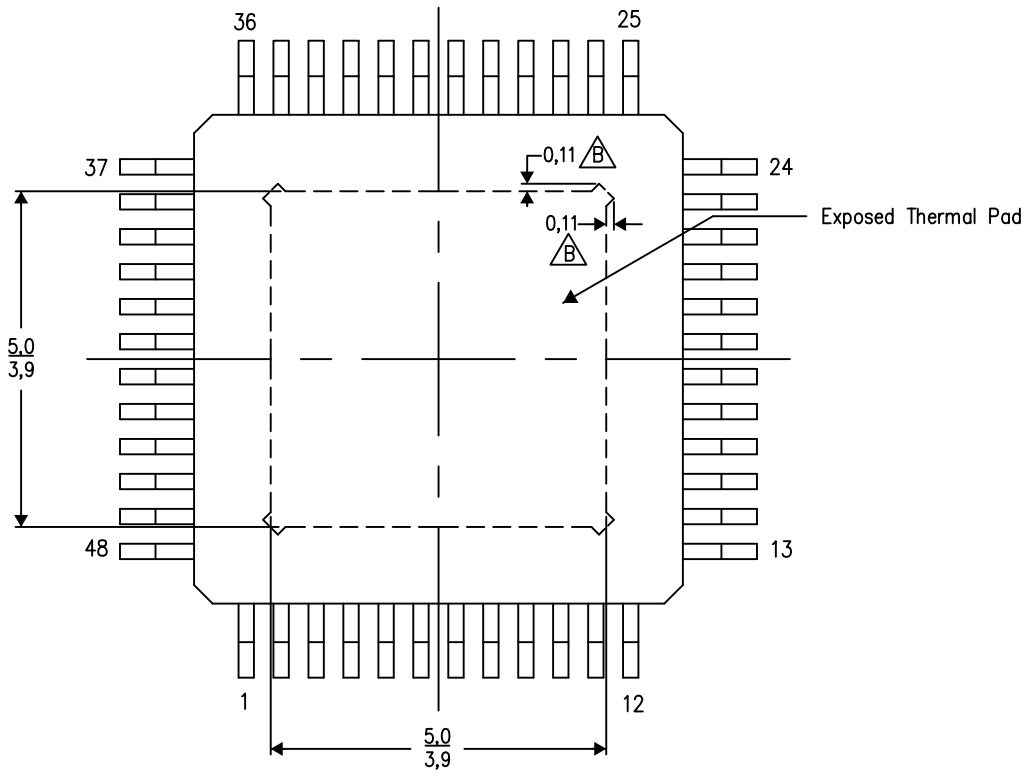
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

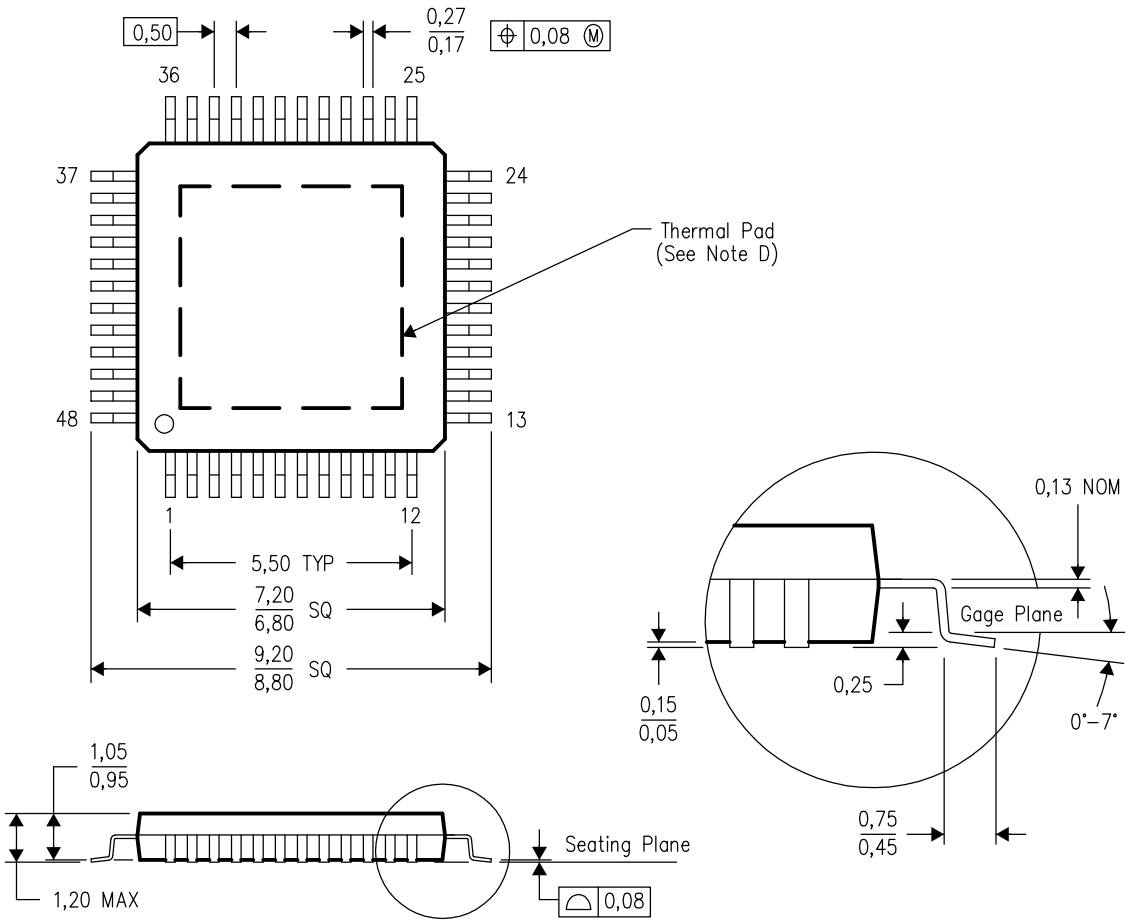
4206329–17/P 03/15

NOTE: A. All linear dimensions are in millimeters

B Tie strap features may not be present.

PowerPAD is a trademark of Texas Instruments

PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MS–026

PowerPAD is a trademark of Texas Instruments.

PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK

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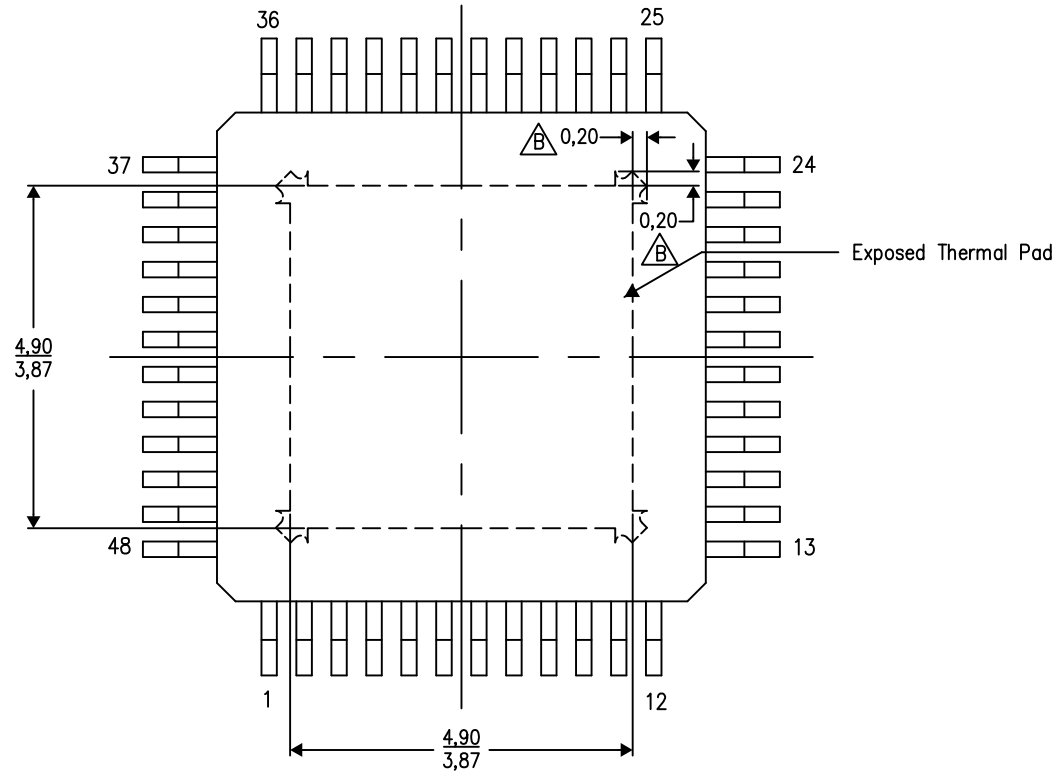

Top View

Exposed Thermal Pad Dimensions

4206329–4/P 03/15

NOTE: A. All linear dimensions are in millimeters

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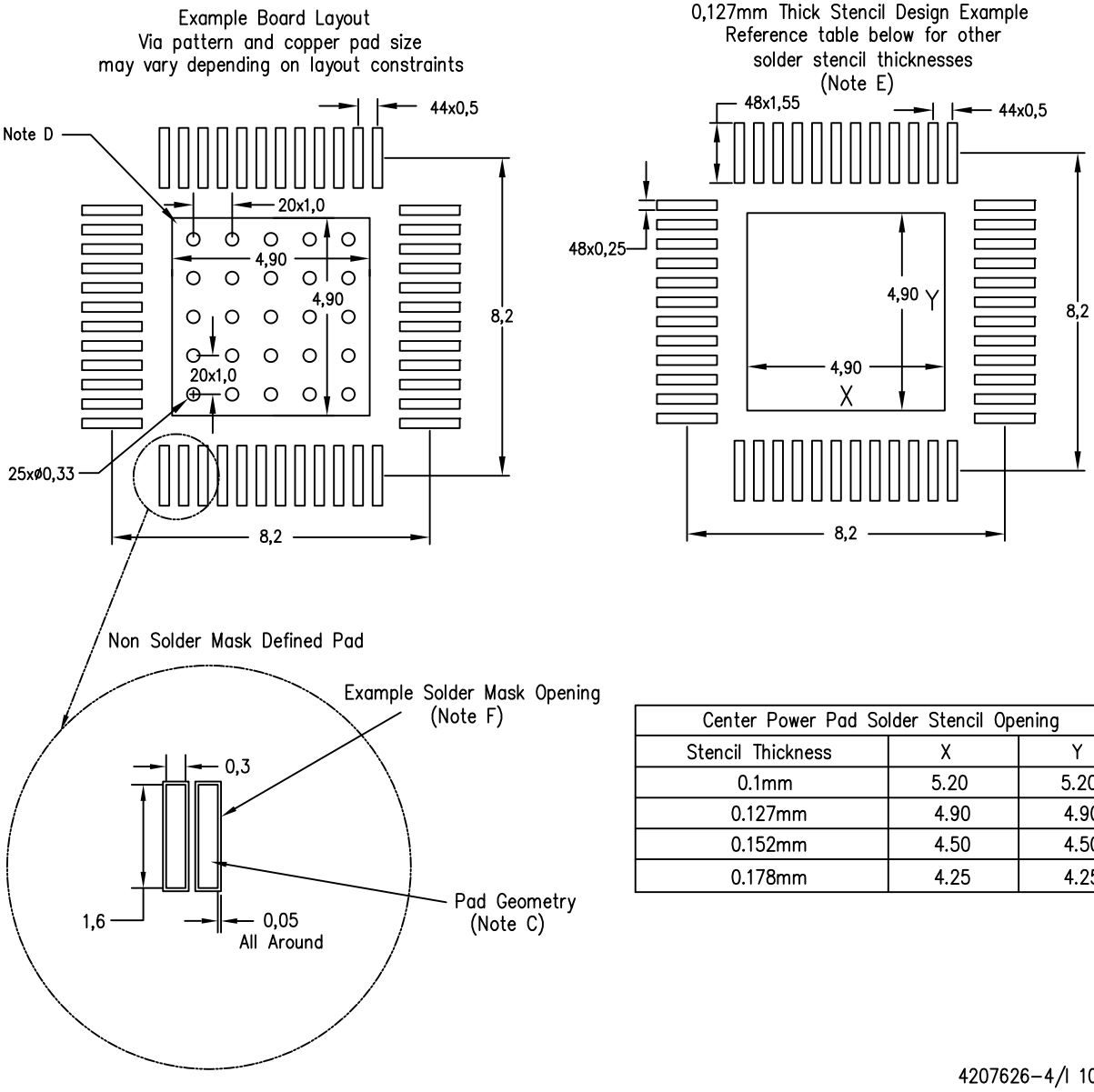
PHP (S–PQFP–G48) PowerPAD™ PLASTIC QUAD FLATPACK



Center Power Pad Solder Stencil Opening		
Stencil Thickness	X	Y
0.1mm	5.20	5.20
0.127mm	4.90	4.90
0.152mm	4.50	4.50
0.178mm	4.25	4.25

4207626–4/I 10/15

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting options for vias placed in the thermal pad.

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Last updated 10/2025